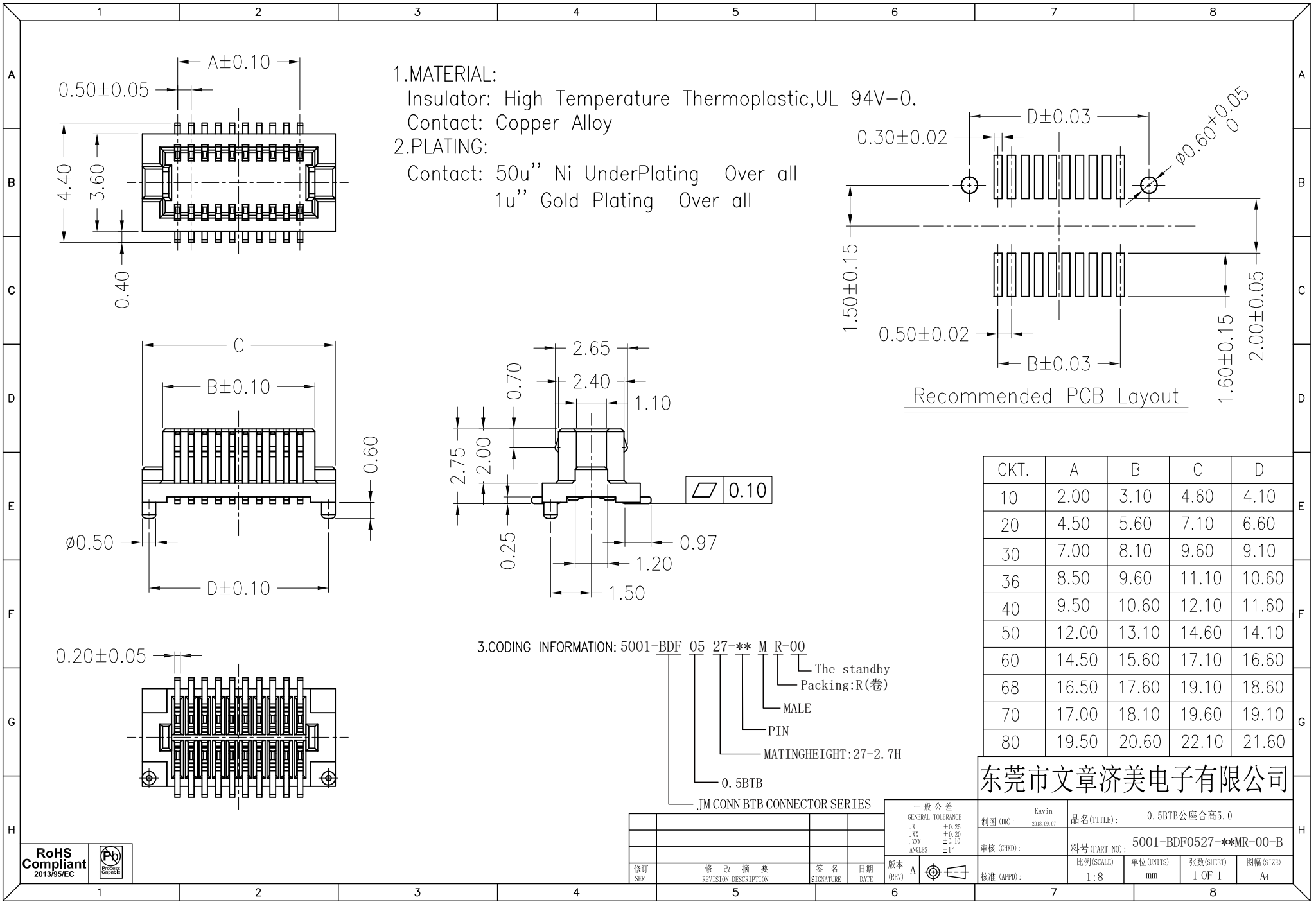




1.MATERIAL:

Insulator: High Temperature Thermoplastic,UL 94V-0.

Contact: Copper Alloy

2.PLATING:

Contact: 50u'' Ni UnderPlating Over all

1u'' Gold Plating Over all

Recommended PCB Layout

CKT.	A	B	C	D
10	2.00	3.10	4.60	4.10
20	4.50	5.60	7.10	6.60
30	7.00	8.10	9.60	9.10
36	8.50	9.60	11.10	10.60
40	9.50	10.60	12.10	11.60
50	12.00	13.10	14.60	14.10
60	14.50	15.60	17.10	16.60
68	16.50	17.60	19.10	18.60
70	17.00	18.10	19.60	19.10
80	19.50	20.60	22.10	21.60

3.CODING INFORMATION: 5001-BDF 05 27-** M R-00

The standby
Packing:R(卷)

MALE

PIN

MATINGHEIGHT:27-2.7H

0.5BTB

JM CONN BTB CONNECTOR SERIES

一般公差
GENERAL TOLERANCE
.X ±0.25
.XX ±0.20
.XXX ±0.10
ANGLES ±1°

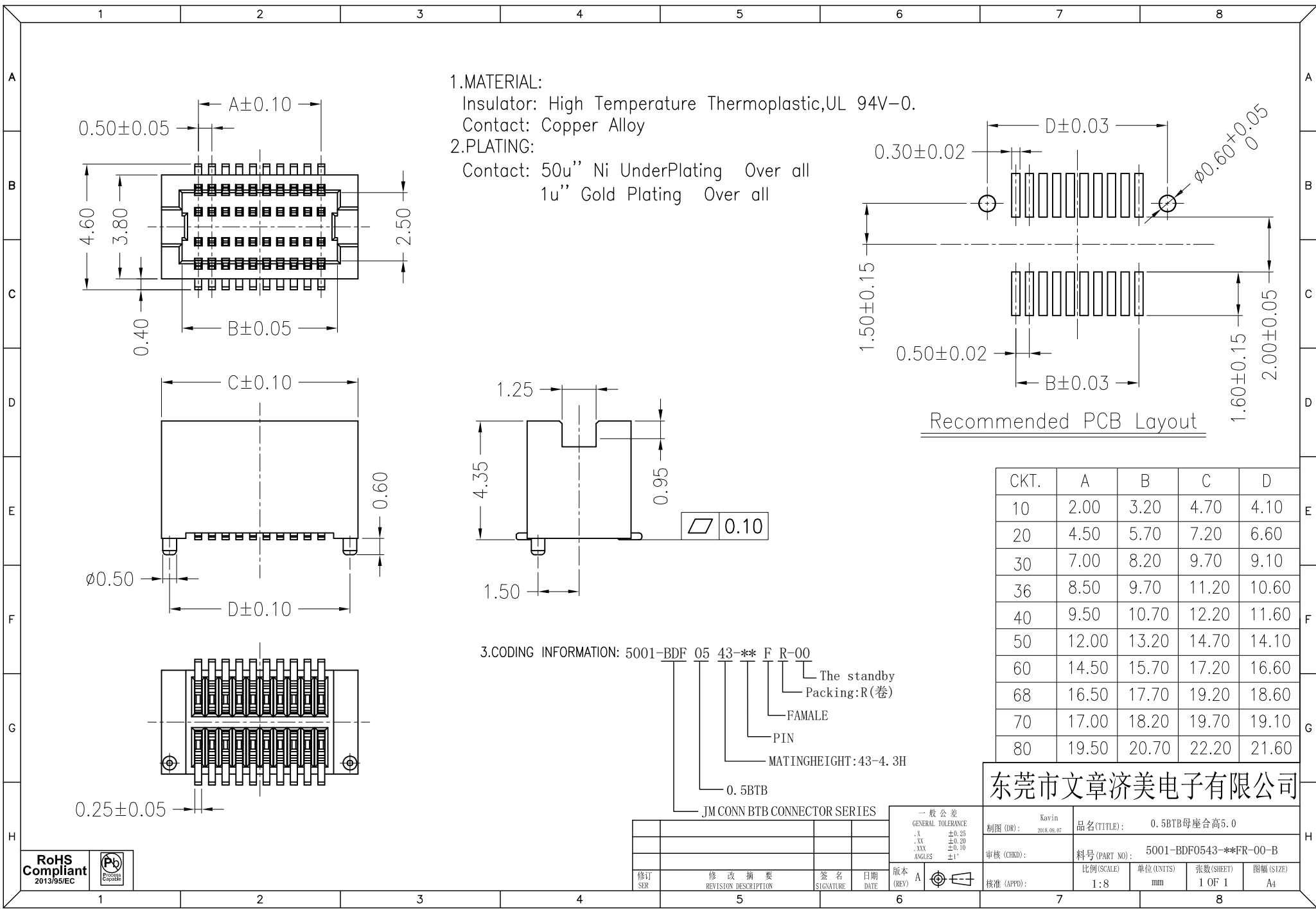
修订 SER	修改摘要 REVISION DESCRIPTION	签名 SIGNATURE	日期 DATE	版本 (REV)

东莞市文章济美电子有限公司

制图 (DR):	Kavin 2018.09.07	品名(TITLE):	0.5BTB公座合高5.0
审核 (CHKD):		料号(PART NO):	5001-BDF0527-**MR-00-B
核准 (APPD):		比例(SCALE):	1:8
		单位(UNITS):	mm
		张数(SHEET):	1 OF 1
		图幅(SIZE):	A4

RoHS
Compliant
2013/5/EC





1.MATERIAL:

Insulator: High Temperature Thermoplastic,UL 94V-0.

Contact: Copper Alloy

2.PLATING:

Contact: 50u" Ni UnderPlating Over all

1u" Gold Plating Over all

Recommended PCB Layout

CKT.	A	B	C	D
10	2.00	3.20	4.70	4.10
20	4.50	5.70	7.20	6.60
30	7.00	8.20	9.70	9.10
36	8.50	9.70	11.20	10.60
40	9.50	10.70	12.20	11.60
50	12.00	13.20	14.70	14.10
60	14.50	15.70	17.20	16.60
68	16.50	17.70	19.20	18.60
70	17.00	18.20	19.70	19.10
80	19.50	20.70	22.20	21.60

3.CODING INFORMATION: 5001-BDF 05 43-** F R-00

The standby
Packing:R(卷)
FEMALE
PIN
MATINGHEIGHT:43-4.3H
0.5BTB
JM CONN BTB CONNECTOR SERIES

东莞市文章济美电子有限公司



制图 (DR):	Kevin	品名(TITLE):	0.5BTB母座合高5.0
审核 (CHKD):	2018.09.07	料号(PART NO):	5001-BDF0543-**FR-00-B
核准 (APPD):		比例 (SCALE):	1:8
		单位 (UNITS):	mm
		张数 (SHEET):	1 OF 1
		图幅 (SIZE):	A4